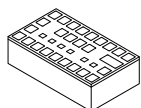


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

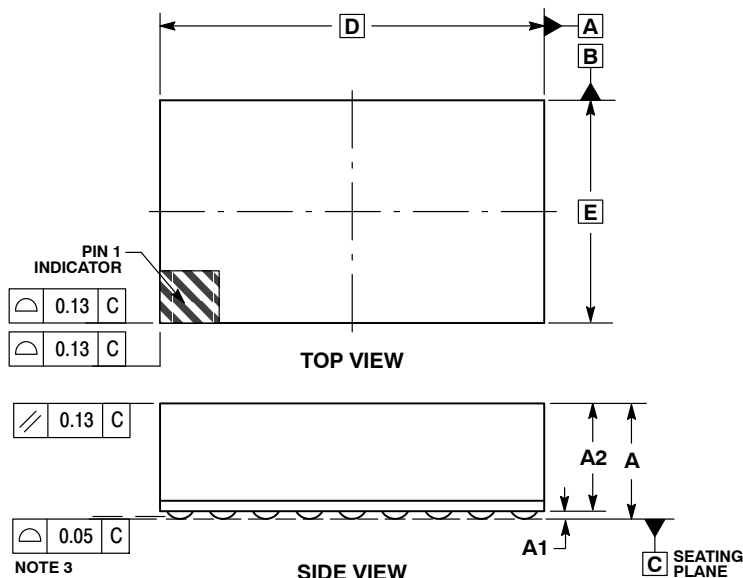
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SIP32 6.35x3.68  
CASE 127DW  
ISSUE O

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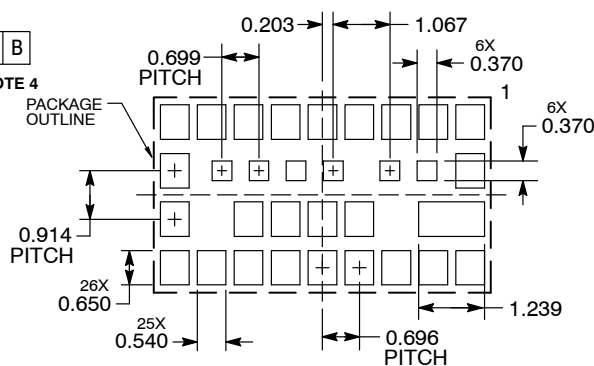
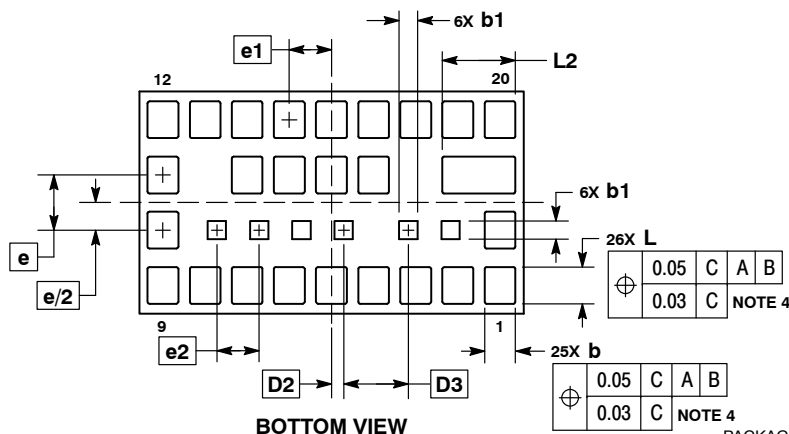
SCALE 2:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BUMPS.
4. DIMENSIONS b, b1, L AND L2 ARE MEASURED AT THE MAXIMUM BUMP DIMENSION PARALLEL TO DATUM C. THE POSITIONAL TOLERANCE APPLIES TO ALL OF THE SOLDER BUMPS.

MILLIMETERS		
DIM	MIN	MAX
A	---	1.960
A1	0.076	0.180
A2	---	1.780
b	0.478	0.538
b1	0.275	0.335
D	6.350 BSC	
D2	0.203 BSC	
D3	1.067 BSC	
E	3.683 BSC	
e	0.914 BSC	
e1	0.696 BSC	
e2	0.699 BSC	
L	0.580	0.640
L2	1.177	1.237



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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